

100 nm Gate Length High Performance Low Power CMOS Transistor Structure

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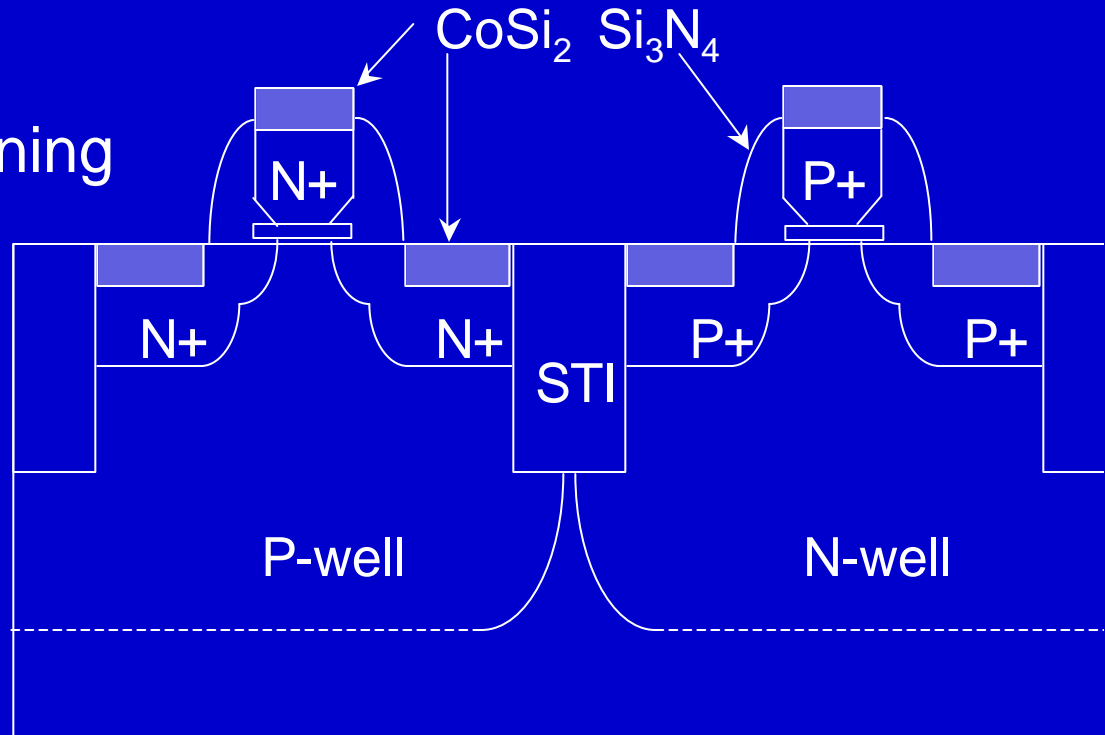
Portland Technology Development, *QRE, #TCAD
Intel Corporation

Outline

- Transistor Features
- Transistor Parametrics
- Performance Benchmarking
- Conclusions

Front End Process Flow and Features

- Shallow Trench Isolation
- Well & V_{TH} Adjust Implants
- Gate Oxide Formation
- Notched Poly Gate Patterning
- Shallow Tip extensions
- Angled Halo Implants
- Si_3N_4 Spacer
- Deep Source/Drain
- Co Salicide
- 1.2~1.6 Volt Operation

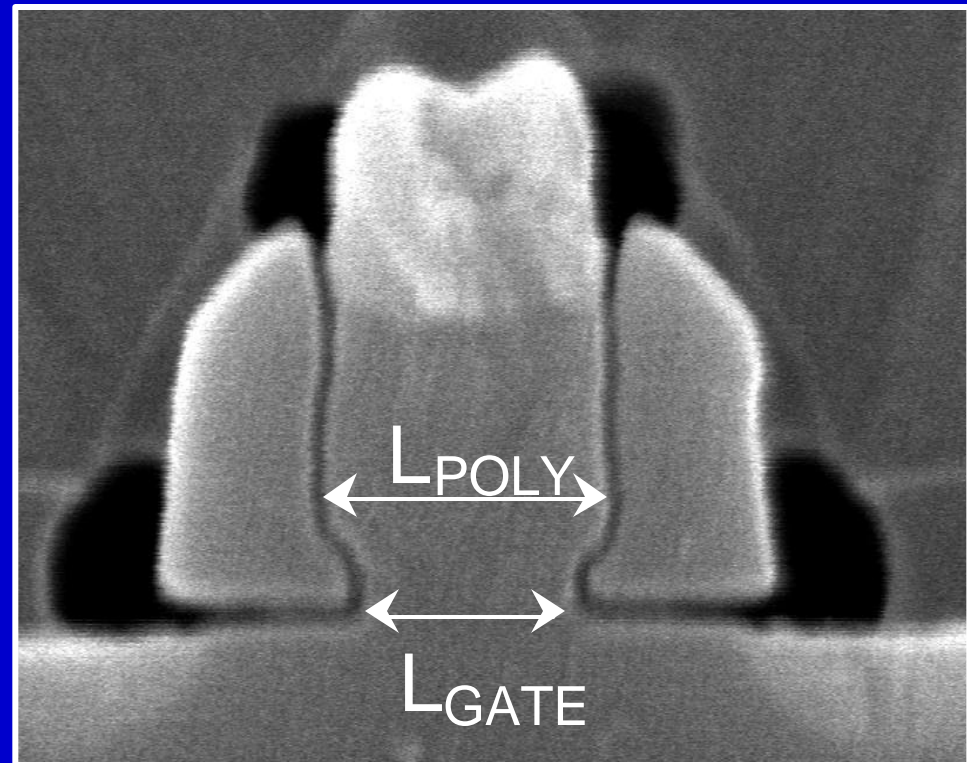


Key Transistor Features Impacting Performance

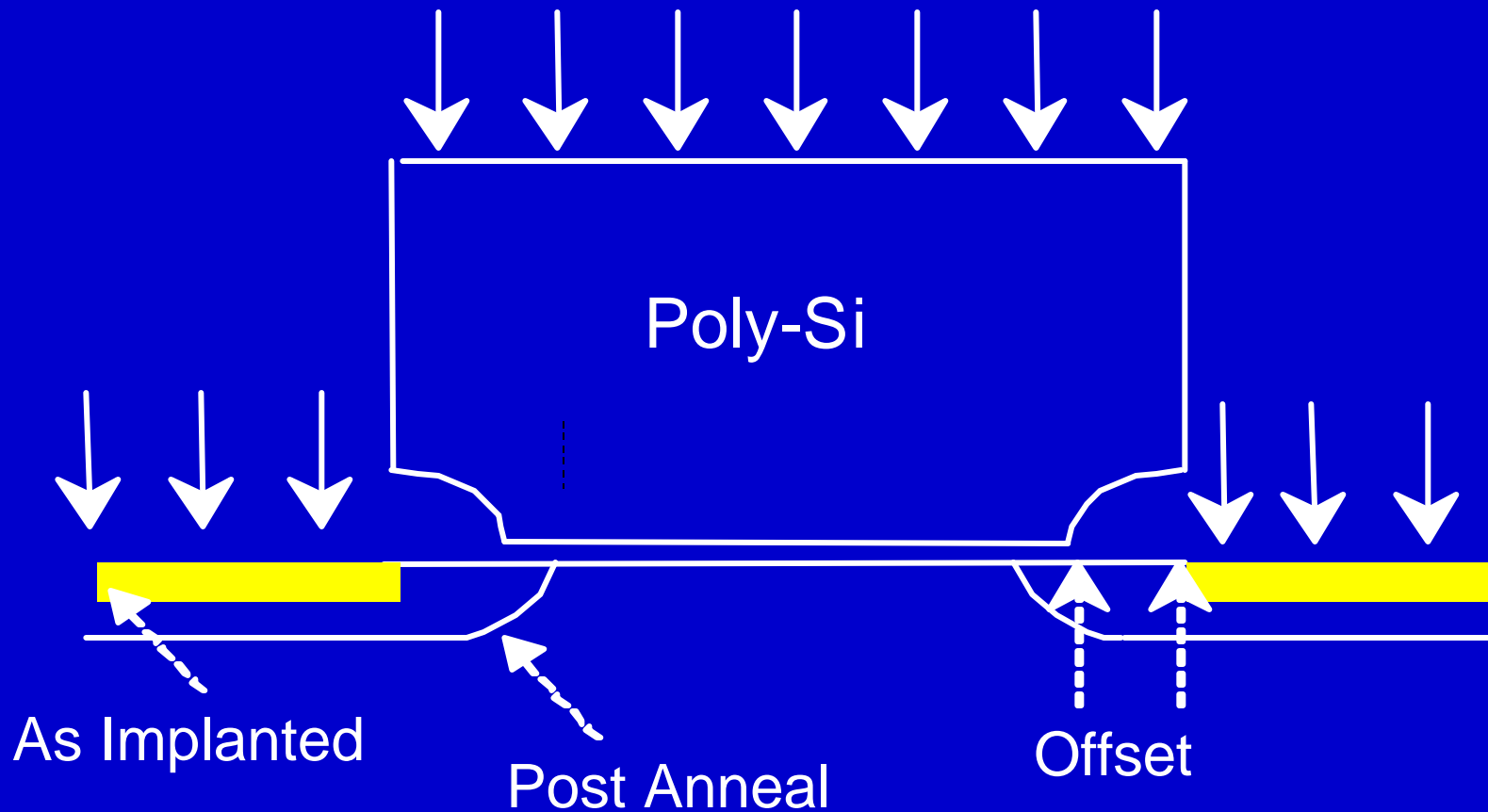
- Notched Poly Profile
- Well Halo Optimization
- 2nm Physical Gate Oxide
- Junction Capacitance Minimization
- Cobalt Silicide

Notched Poly Profile

- Advantages of Poly Notch:
 - C_{GATE} reduction
 - Lower salicide resistance at a given L_{GATE}
 - High I_{DSAT} at low Miller Cap
- Cost-Free Process
- $L_{POLY} = 130nm$
 $L_{GATE} = 100nm$

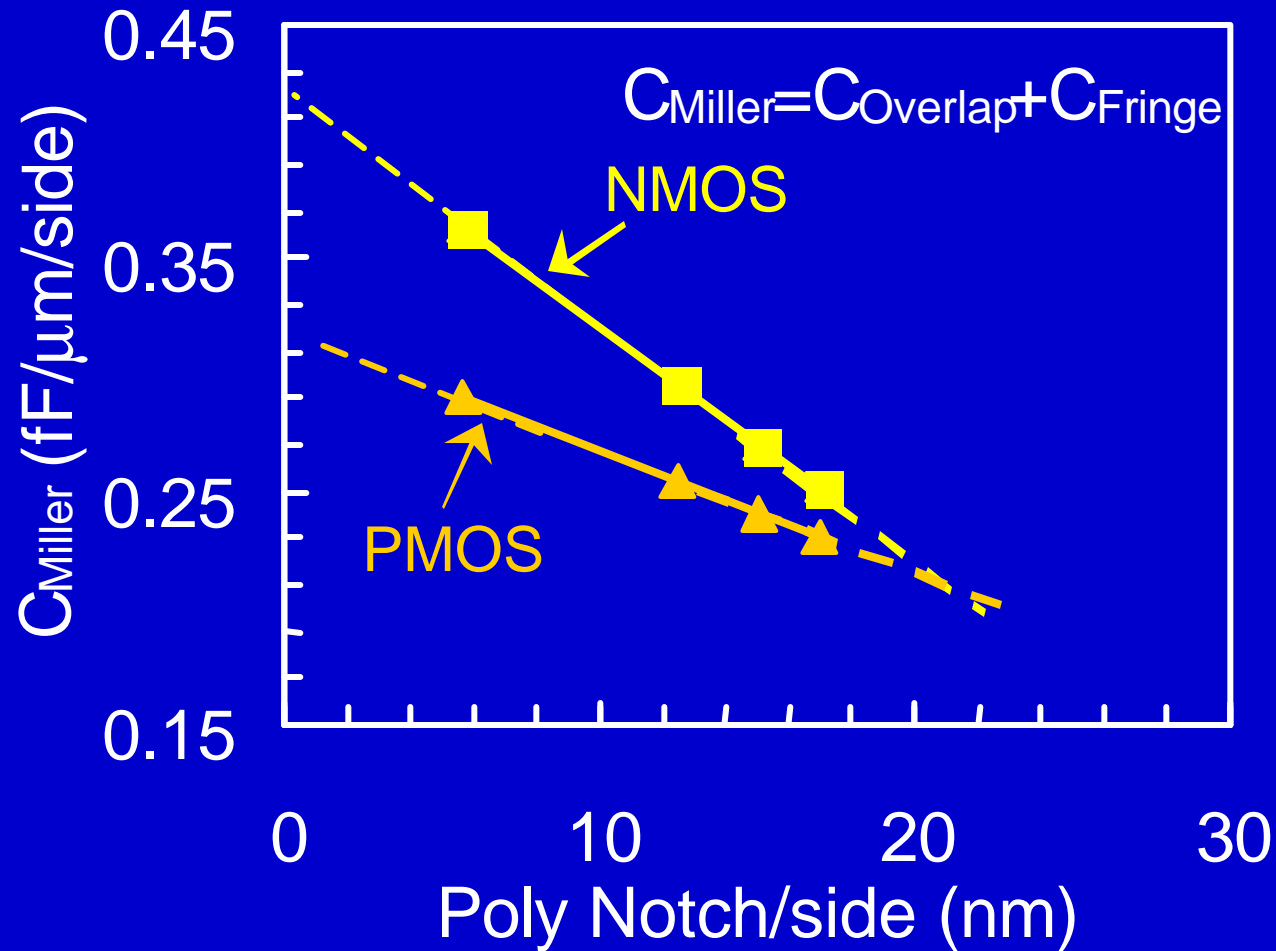


SDE Formation with Poly Notch



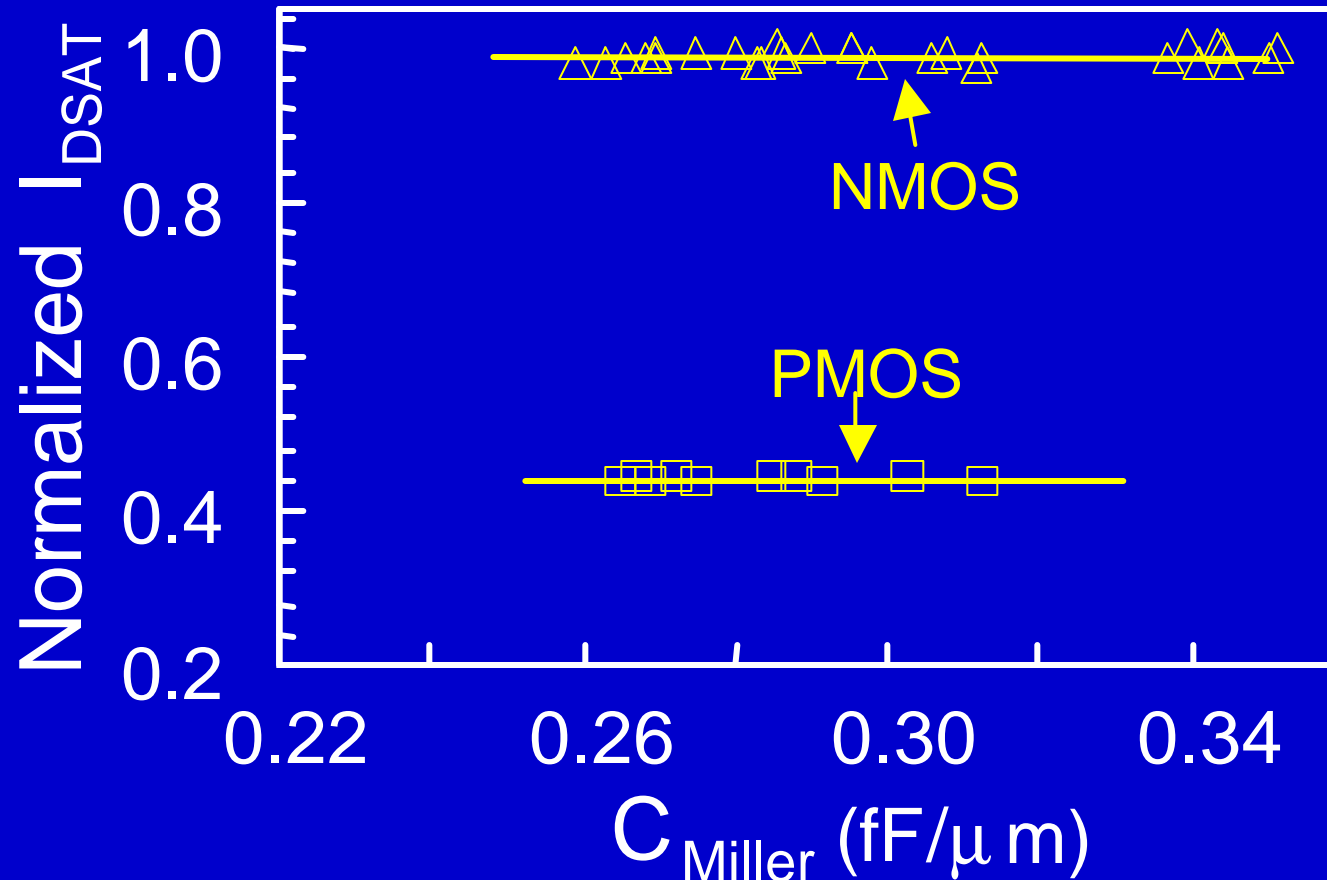
- Heavily doped SDE regions obtained at minimal under-diffusion

C_{MILLER} Modulation with Poly Notch



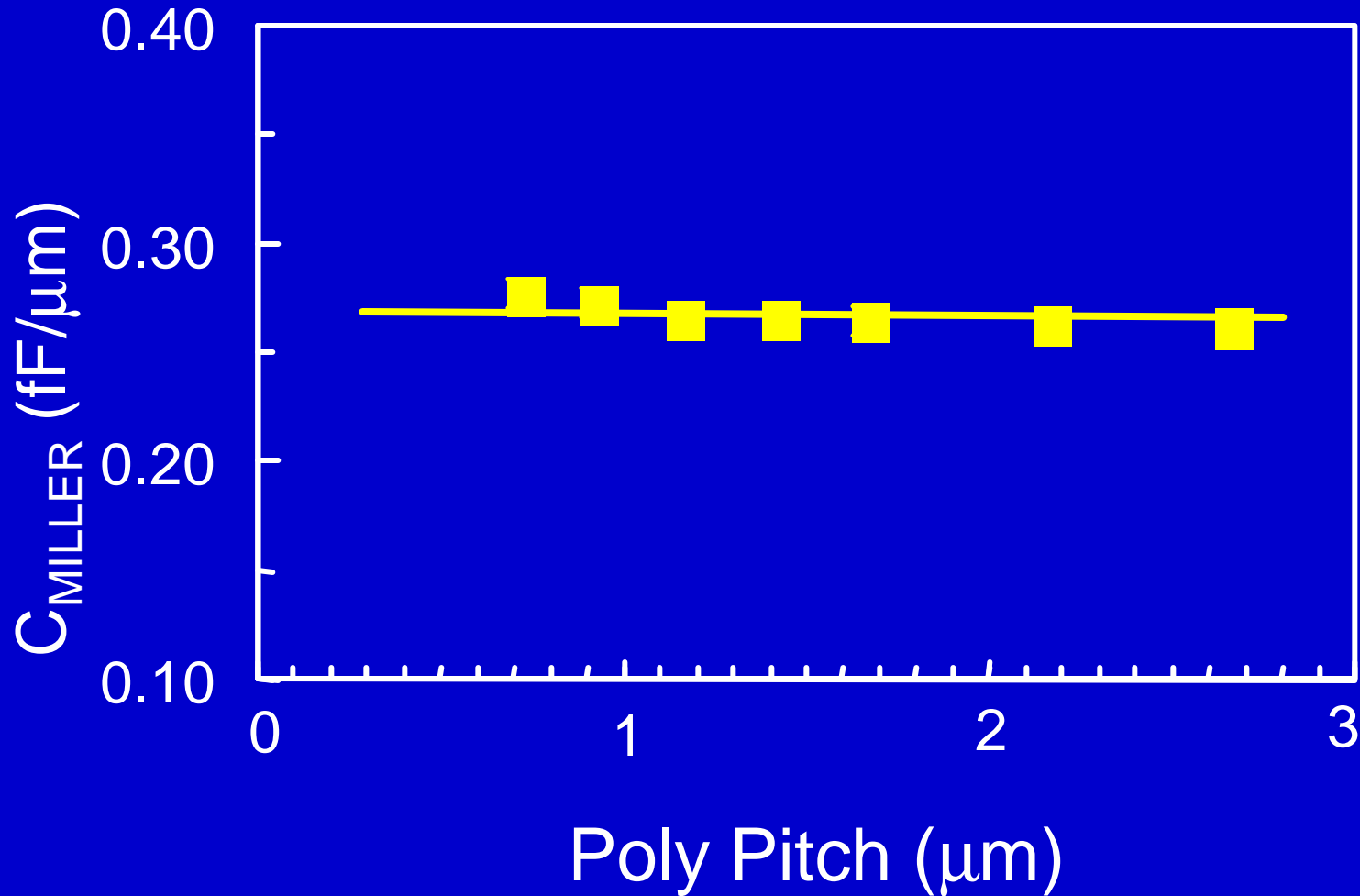
- C_{MILLER} modulates linearly with poly notch size

I_{DSAT} vs. C_{MILLER} Characteristics



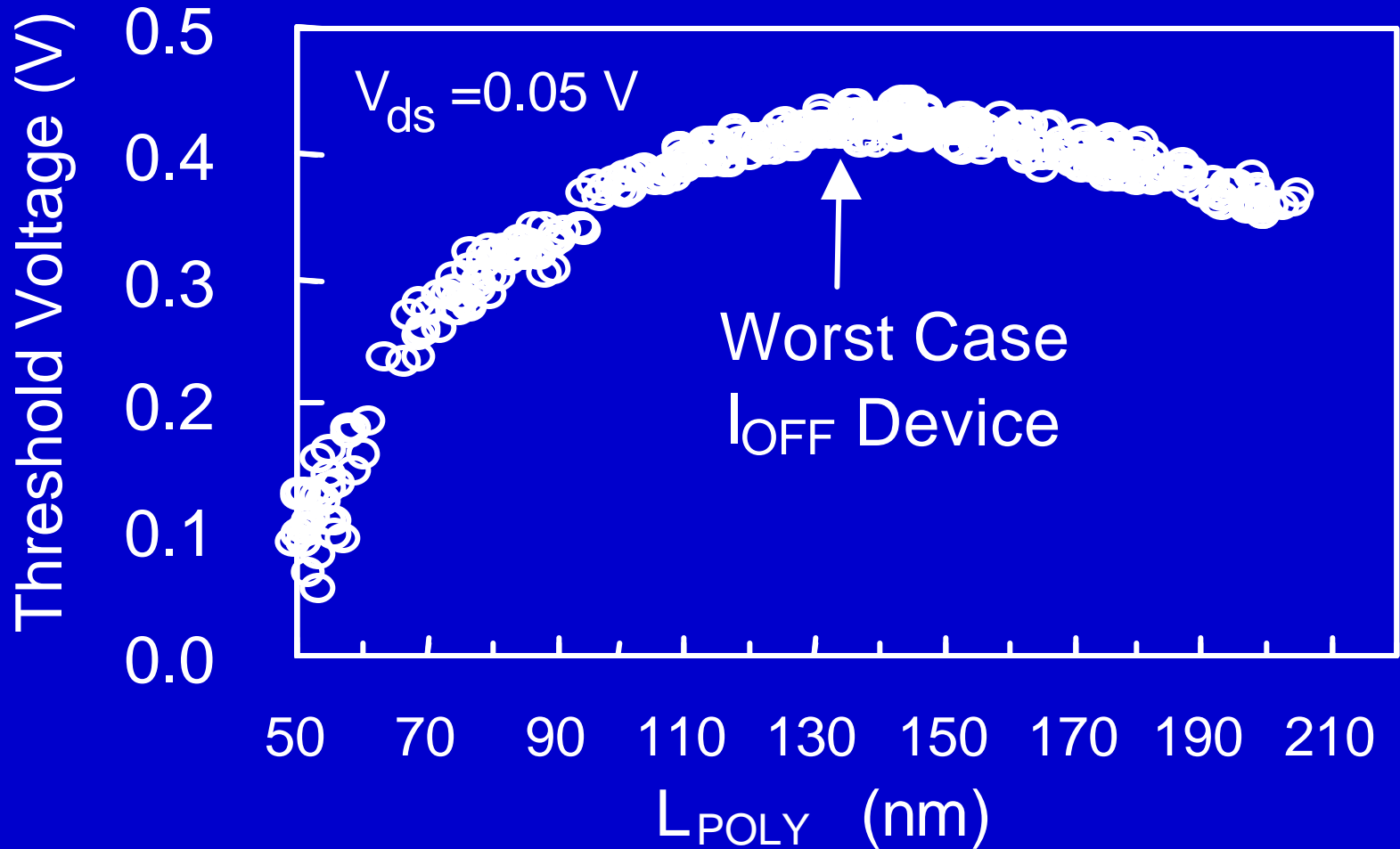
- High I_{DSAT} demonstrated at low C_{MILLER} with “Notched-Poly” process

Poly Notch Process Control



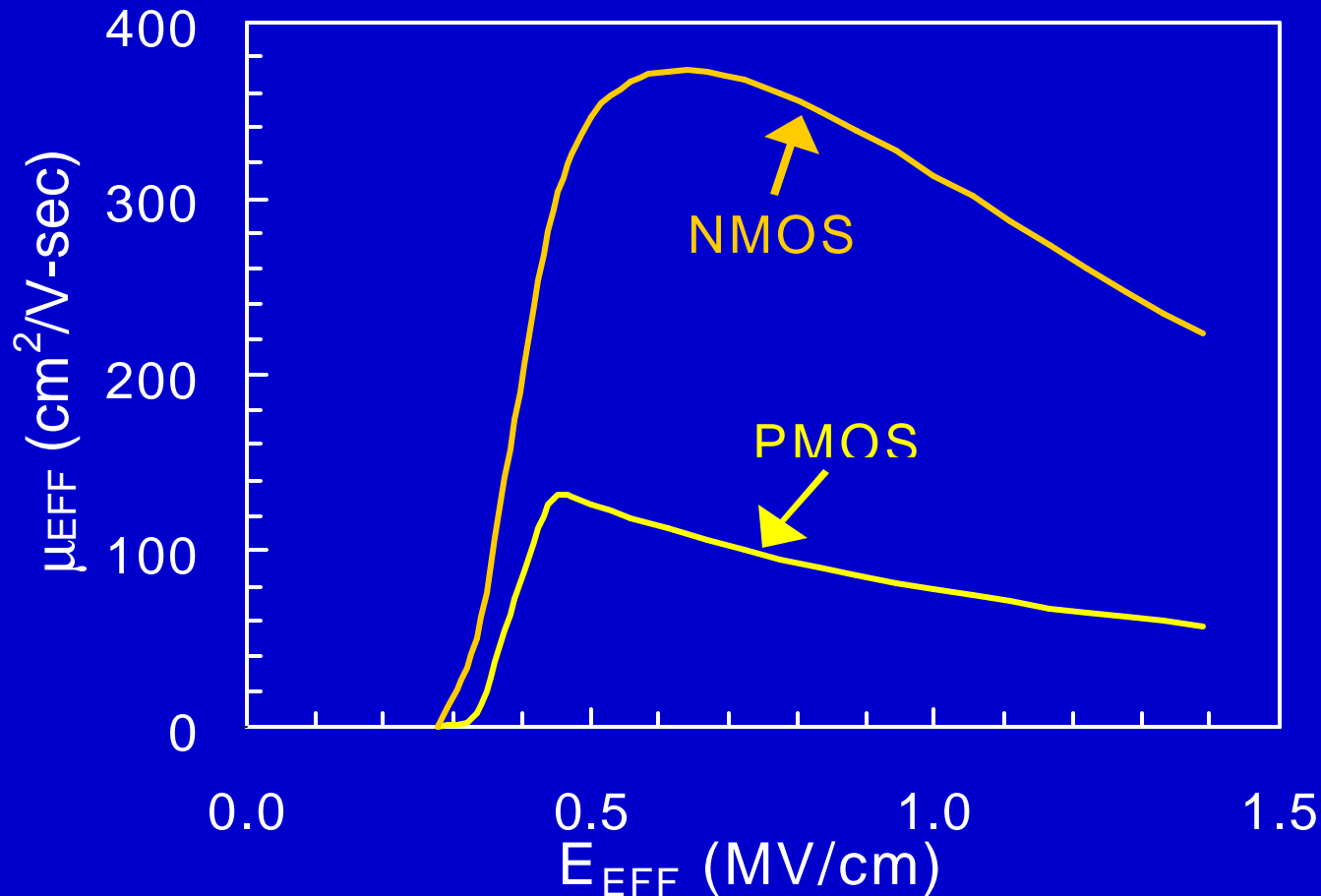
- Poly notch dimension is insensitive to poly pitch **intel**

Well-Halo Optimization



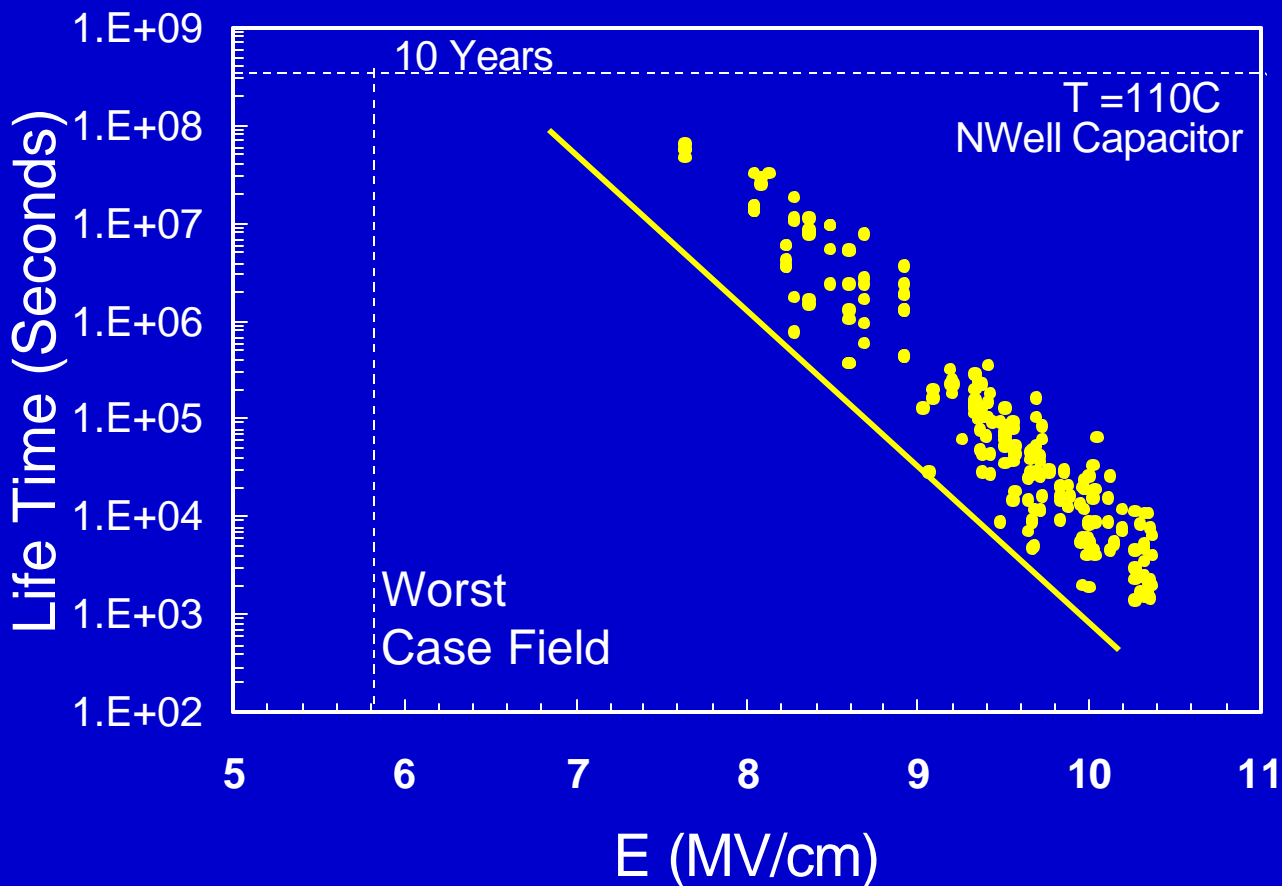
- Well Halo combination optimized to minimize performance degradation between worst case & target devices

Electron and Hole Channel Mobility



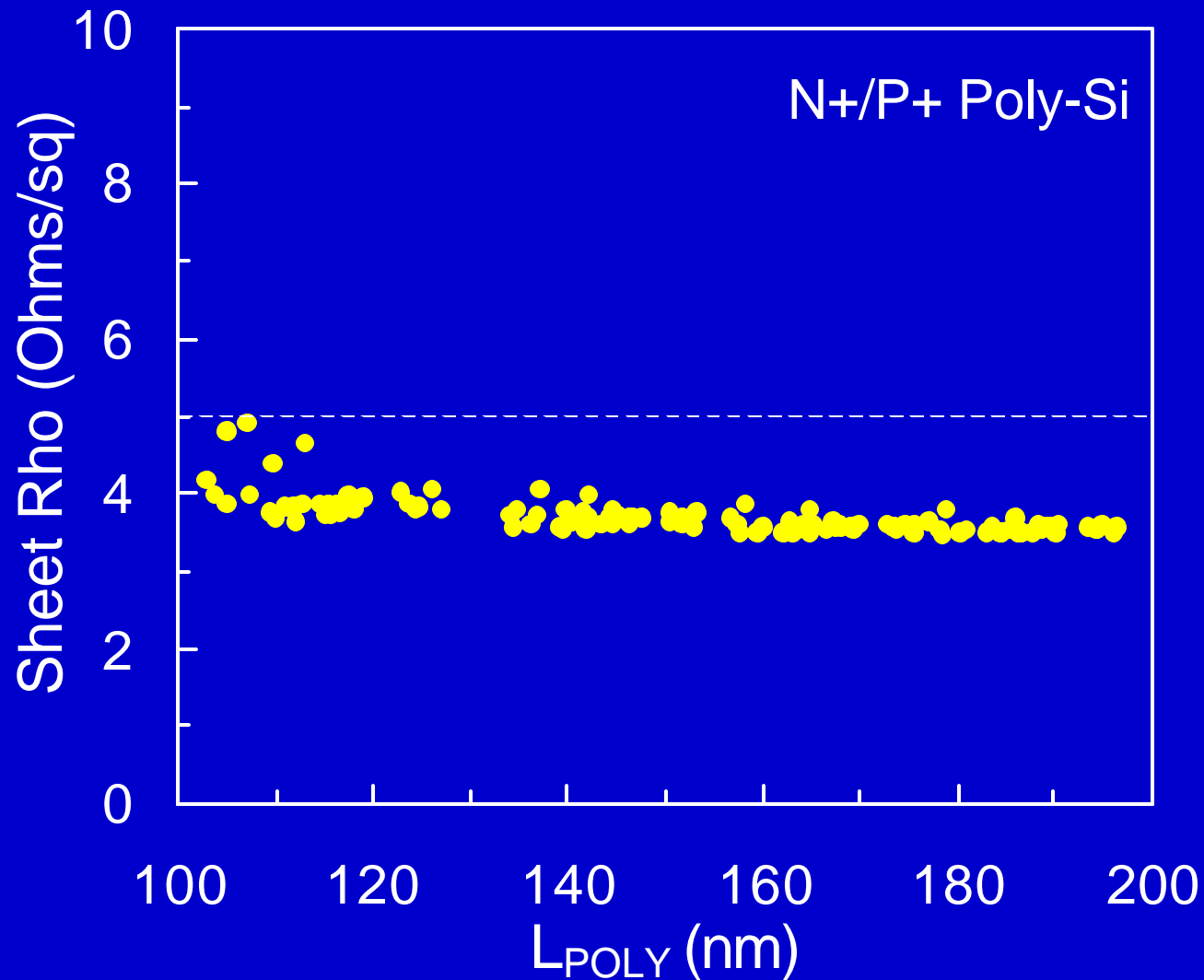
- High NMOS & PMOS mobility demonstrated for devices with 2nm thick physical oxide

2nm Physical Gate Oxide Lifetime

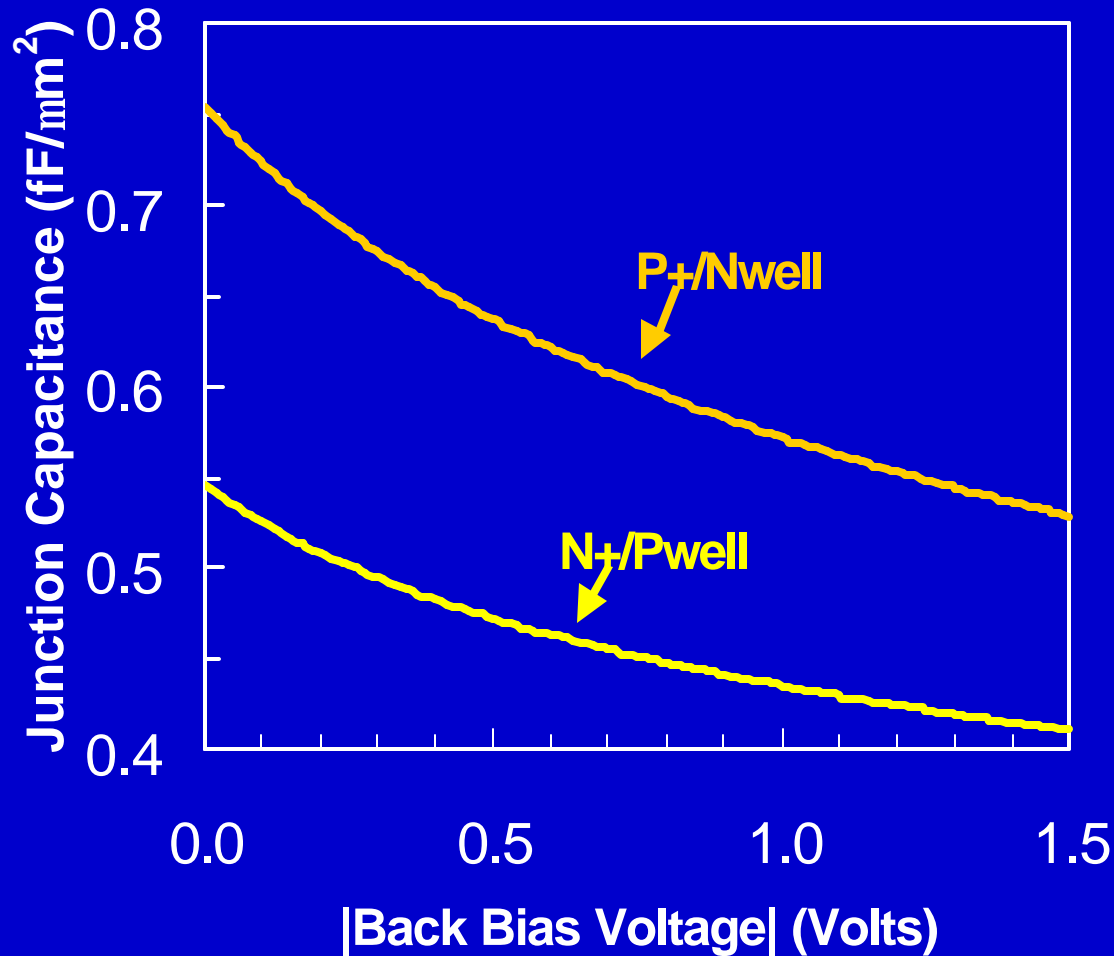


- Some data points correspond to 1.5 years stress
- Product V_{CC} is set based on oxide area and temperature
- Gate oxide meets 10 years life time criteria

Co Salicide Electrical Results



Area Junction Capacitance



- Very low C_{JA} achieved without compromising isolation

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Transistor Parameters Summary

1998 IEDM

This Work

NMOS

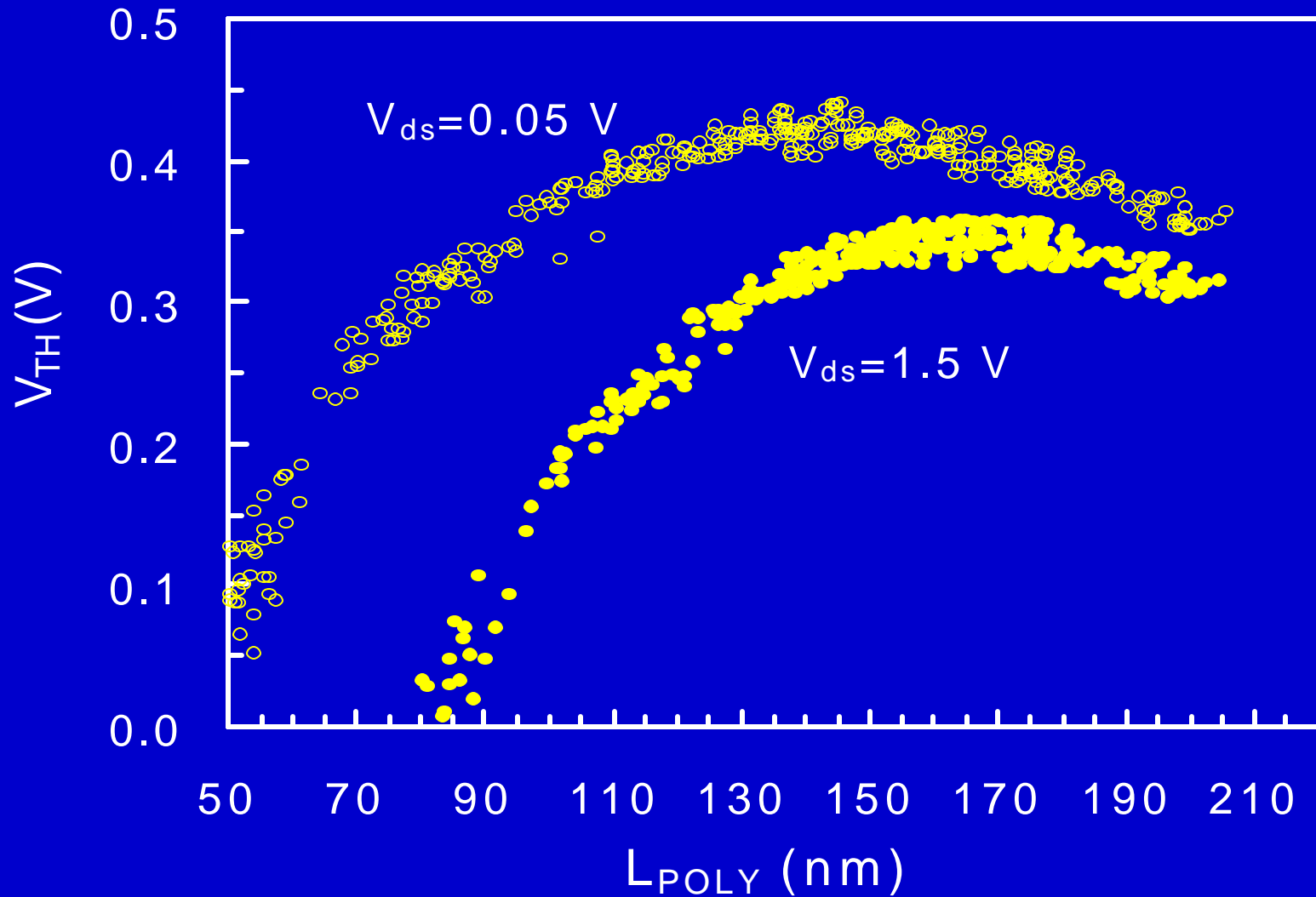
PMOS

NMOS

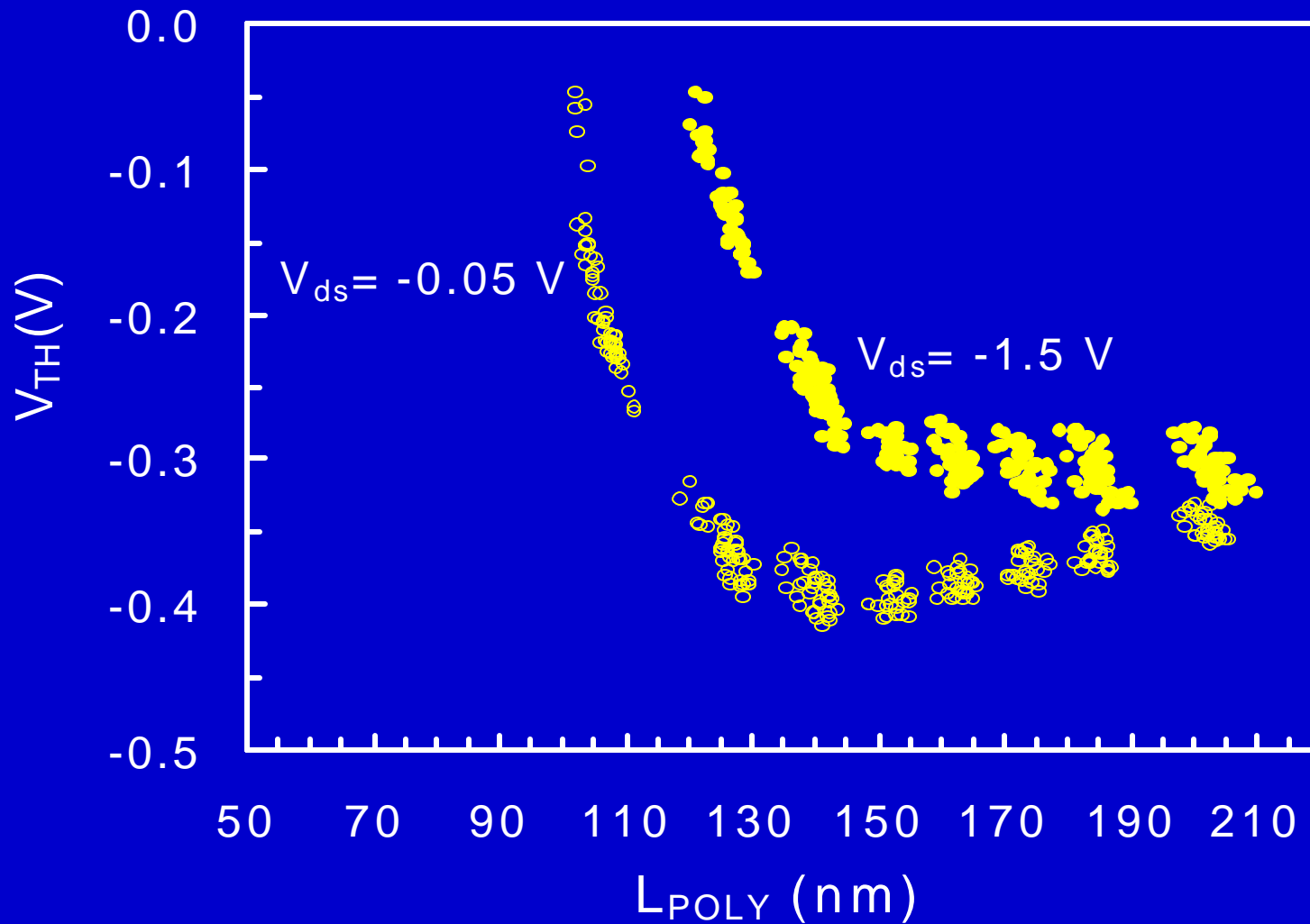
PMOS

L_{POLY}	130	150	130	135	nm
V_T (at 1.5V V_D)	290	-230	290	-230	mV
I_{D_SAT} (at 3 nA I_{OFF})	0.94	0.42	1.04	0.46	mA/um
C_{MILLER}	0.27	0.24	0.27	0.24	fF/um
C_J (at 0V bias)	0.65	0.80	0.55	0.75	fF/um ²

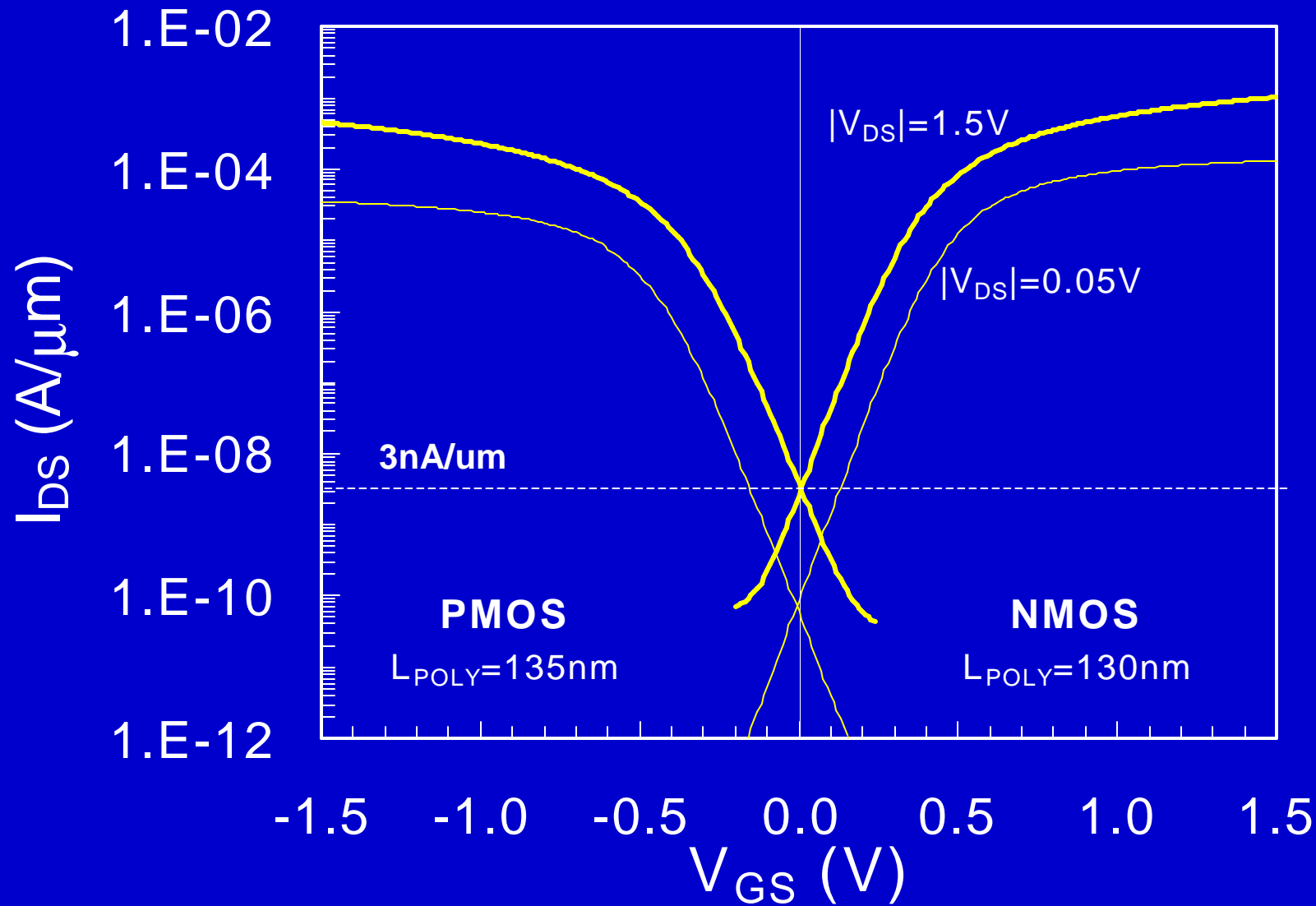
NMOS V_T vs. L_{POLY}



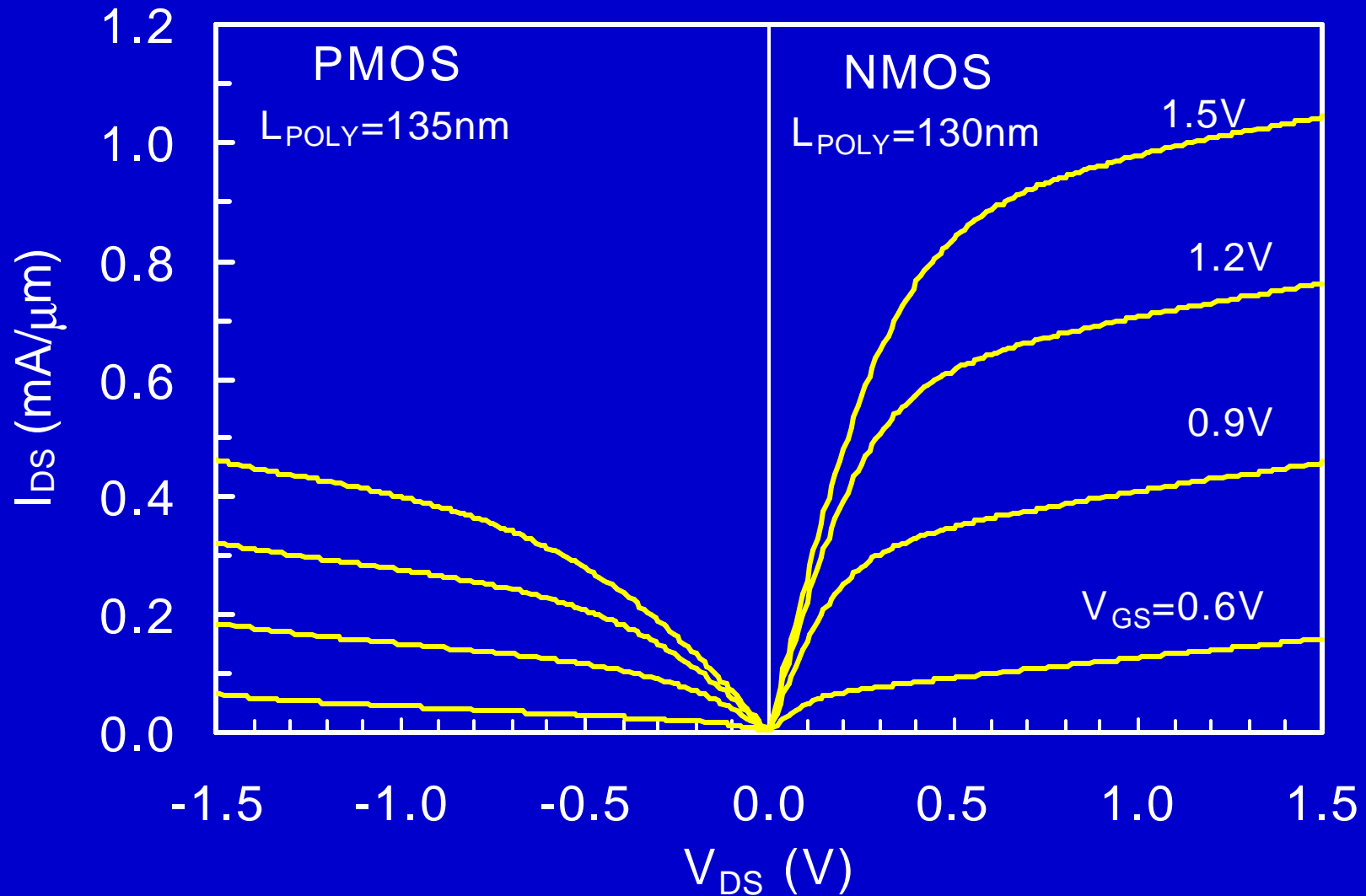
PMOS V_T vs. L_{POLY}



Sub-threshold Characteristics



Transistor I-V Characteristics



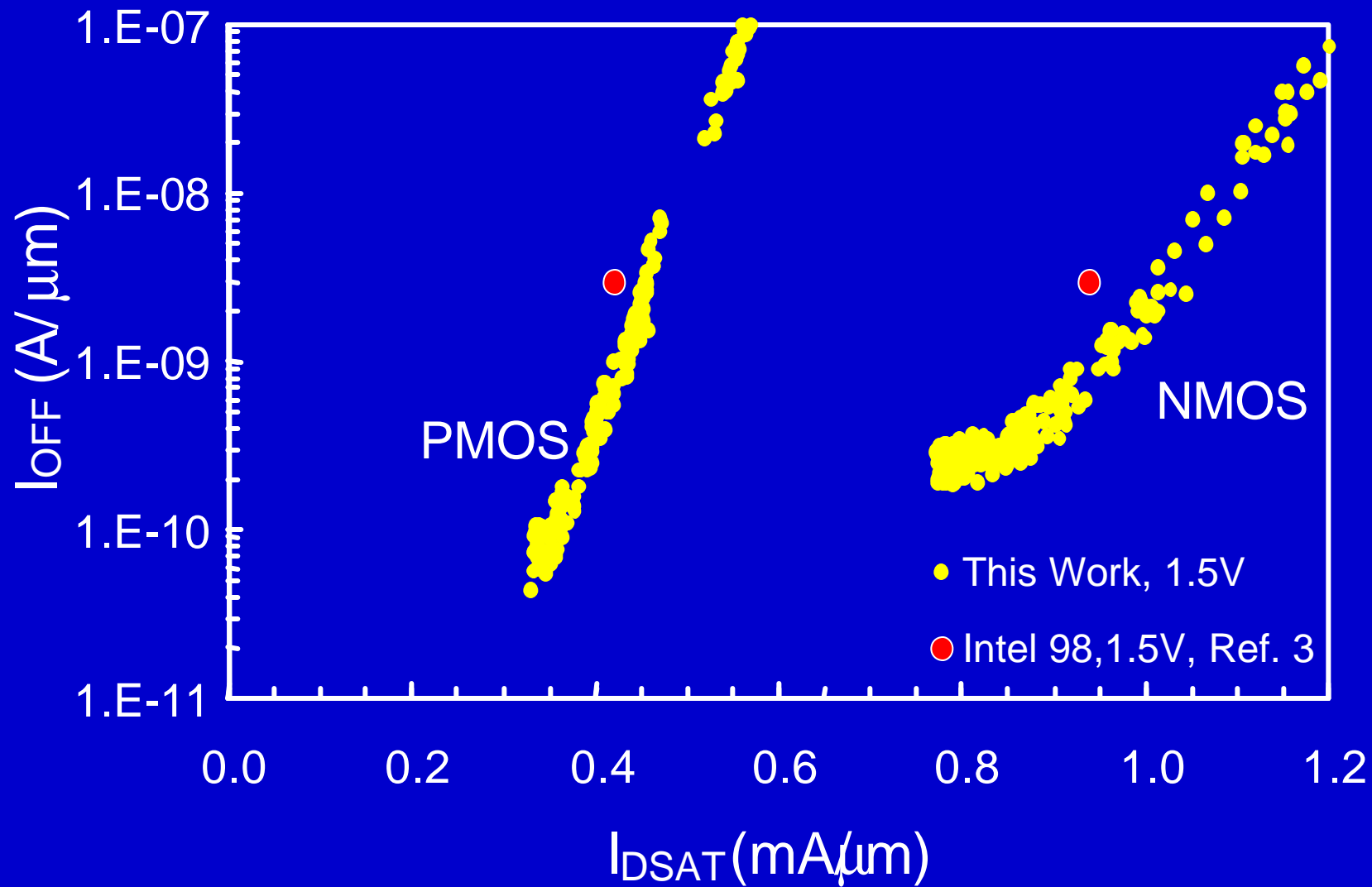
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- **Performance Benchmarking**
- SRAM Performance
- Conclusions

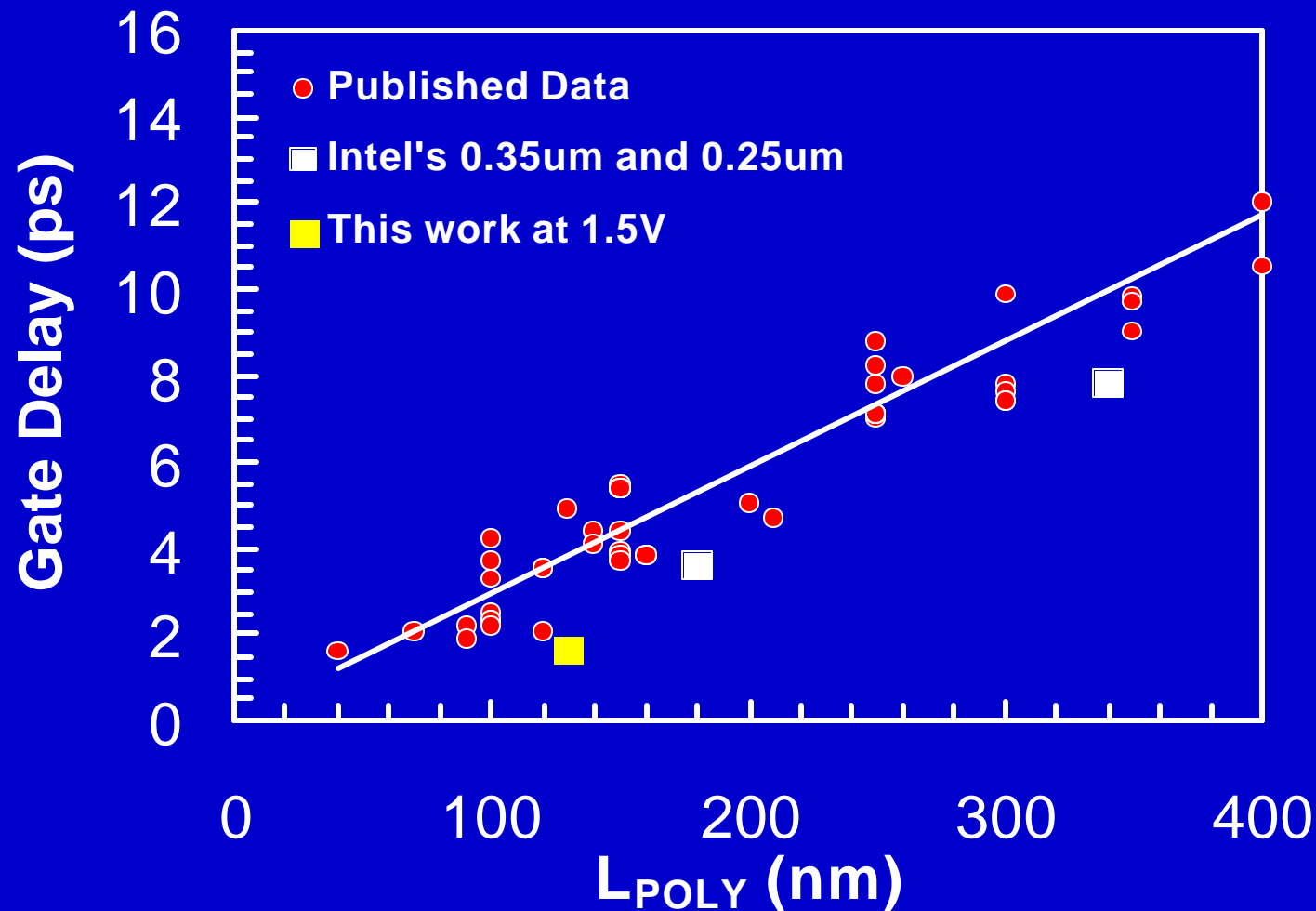
Performance Metrics

- Drive Current vs Off Current (I_{ON} vs I_{OFF})
- $C_g V_d / I_d$ Gate Delay
- Energy-Delay Product
- FO=1 Ring Oscillator Delay
- SRAM performance

I_{ON} VS I_{OFF}

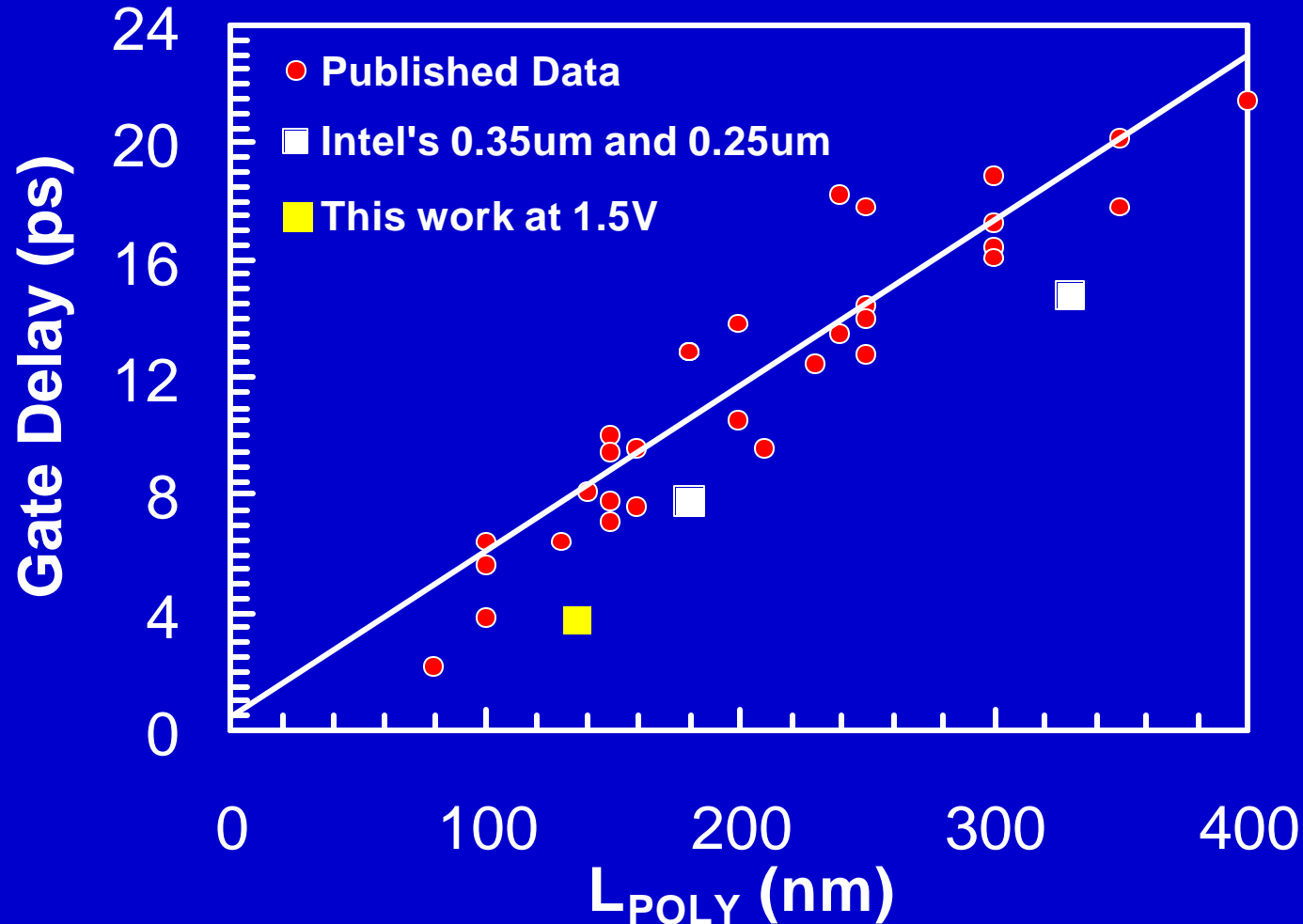


NMOS CV/I Gate Delay



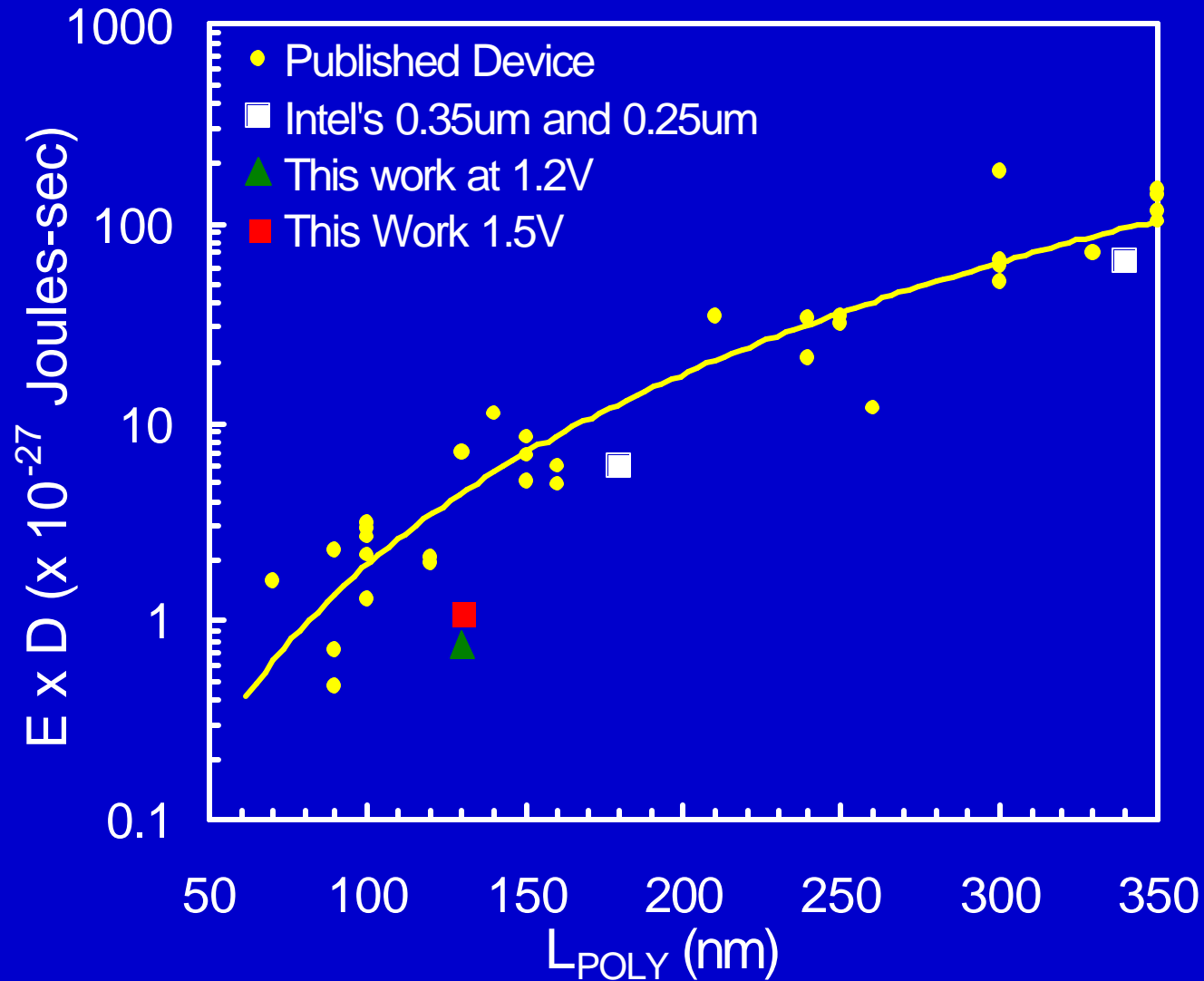
- NMOS CV/I Delay at $3nA/\mu m$ I_{OFF} is 1.65 psec

PMOS CV/I Gate Delay

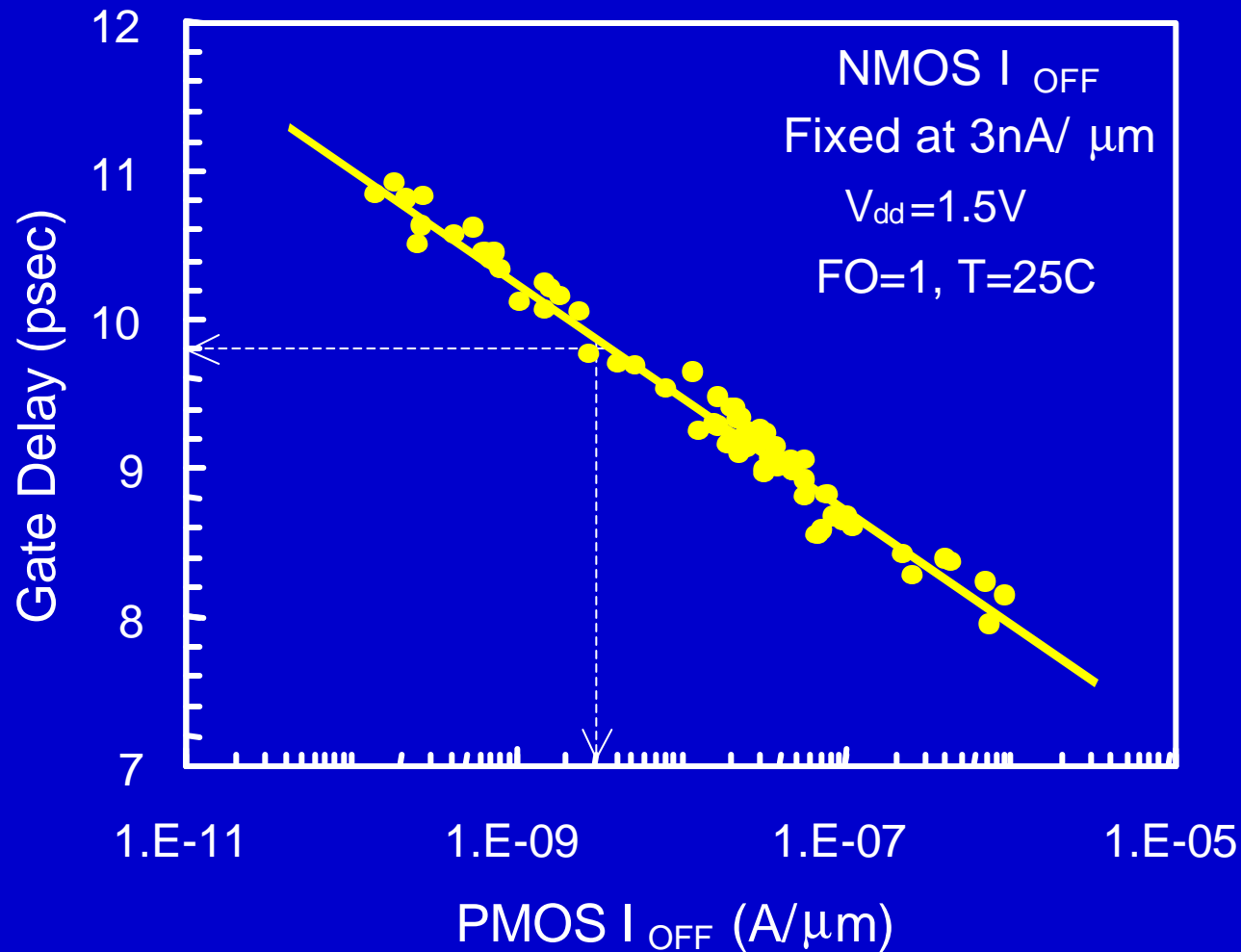


- PMOS CV/I Delay at $3\text{nA}/\mu\text{m}$ I_{OFF} is 3.78 psec

NMOS Energy x Delay



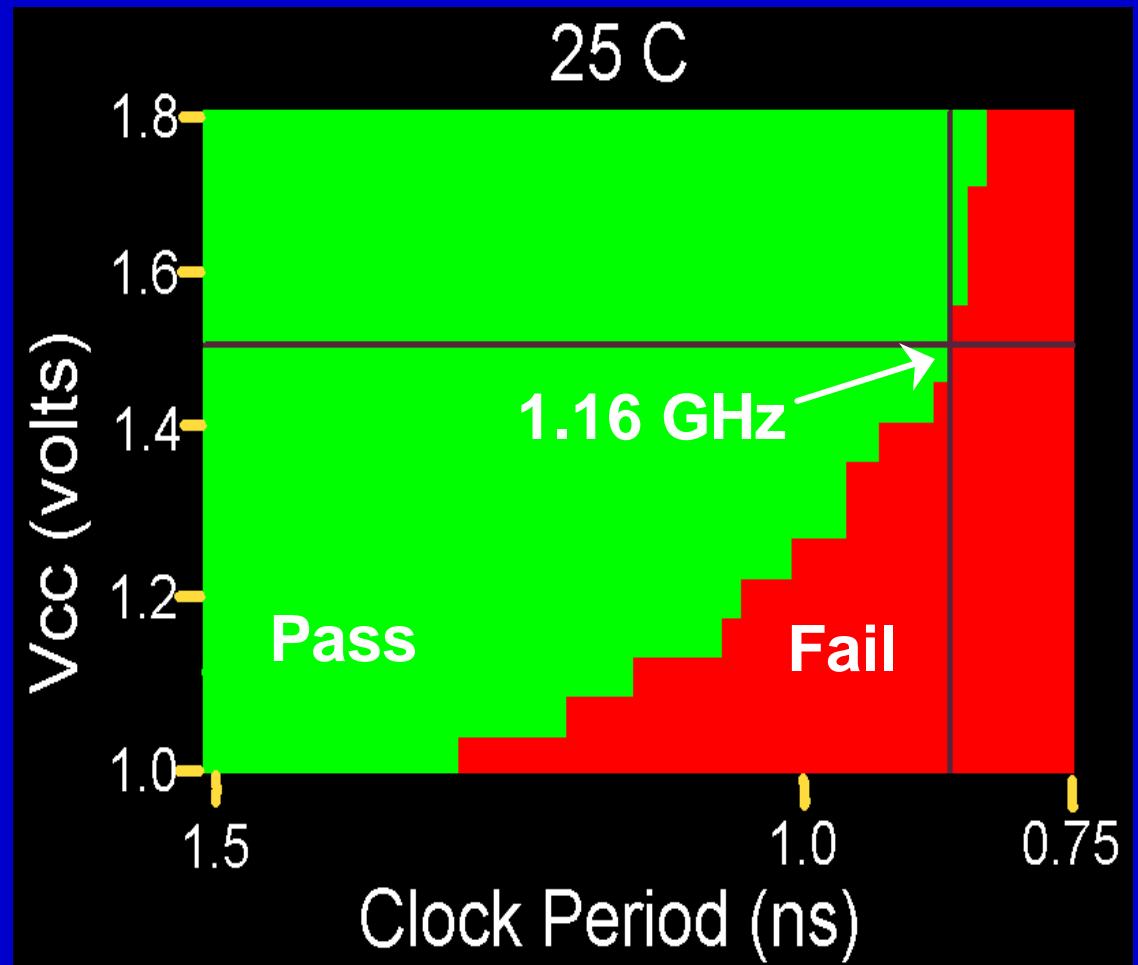
Ring Oscillator Delay per Stage



- Sub-10 psec RO delay measured at 1.5V at $3nA/m$ I_{OFF}

16 Mbit SRAM Shmoo Plots

- >100 million transistors
- 1.16 GHz SRAM @ 1.5V
- > 800MHz Pentium® III Microprocessors
(More details at ISSCC '2000)



Conclusions

- High performance/low power 100nm L_{GATE} transistor structure presented.
- The best reported I_{on} vs I_{off} characteristics at 1.5V.
- Performance trend better than industry in CV/I and ExD metrics.
- Sub 10ps inverter delay at very moderate I_{OFF} demonstrated.
- 16 MB SRAM yield learning vehicle operates at 1.16 GHz.
- These transistors incorporated in Intel's 180nm logic technology

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- Sort and Test Technology Development Group.
- TEM Lab of Oregon Q&R Group.